

CERTIFICATION OF COMPLIANCE AND CHEMICAL CONTENT

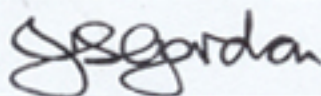
The undersigned, an employee and authorized representative of National Semiconductor, certifies that to the knowledge of National Semiconductor as of the date below:

- ❖ Substances listed in *Table of Banned Substances* are not intentionally added to National Semiconductor products and packing materials, except lead in solder and ceramics.
- ❖ Lead-free products, which are designated "NOPB," are compliant with European Union Directive on the restriction of the use of certain hazardous substances in electrical and electronic equipment (RoHS). Performance requirements of certain specialized products necessitate the use of RoHS exempt high melting temperature tin/lead solder alloy or ceramics containing lead. If designated "NOPB," these products are also RoHS compliant.
- ❖ Trace impurity concentrations of banned substances are < RoHS or other regulatory limits.
- ❖ Trace impurity concentration of cadmium in plastic materials is < 5ppm.
- ❖ National Semiconductor products do not contain and are not manufactured with substances subject to The Montreal Protocol on Substances that Deplete the Ozone Layer and U.S. Clean Air Act, Title VI, i.e. ozone depleting substances.

Table of Banned Substances

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- Asbestos
 - Azo compounds
 - Cadmium and cadmium compounds
 - Ethylene glycol ethers and related compounds
 - Halogenated dioxins and furans
 - Hexavalent chromium compounds
 - Lead and lead compounds
 - Mercury and mercury compounds
 - Ozone depleting substances
 - Polybrominated biphenyls (PBBs) and diphenyl ethers (PBDEs)
 - Polychlorinated biphenyls (PCBs), phenyls, terphenyls and naphthalenes
 - Radioactive substances
 - Short chain chlorinated paraffins
 - Tributyltin, bis(tributyltin) oxide, triphenyltin, and other organic tin compounds
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Signature: _____



Name/Title: _____ Jim Gordon, Vice President of Quality _____

Date: _____ April 23, 2004 _____